

STPS4030CT/CG/CR

LOW DROP POWER SCHOTTKY RECTIFIER

MAJOR PRODUCTS CHARACTERISTICS

I _{F(AV)}	2 x 20 A
V _{RRM}	30 V
Tj (max)	150°C
V _F (max)	0.40 V

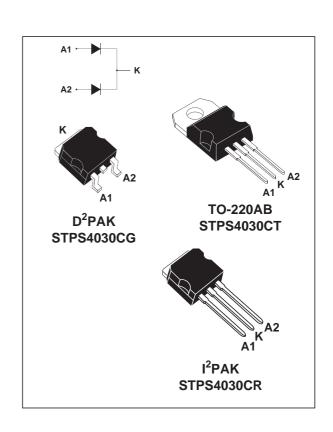
FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- EXTREMELY FAST SWITCHING
- LOW FORWARD VOLTAGE DROP FOR HIGHER EFFICIENCY
- LOW THERMAL RESISTANCE
- AVALANCHE CAPABILITY SPECIFIED

DESCRIPTION

Dual Schottky rectifier suited for switch Mode Power Supply and high frequency DC to DC converters

Packaged in TO-220AB, D²PAK and I²PAK, this device is intended for use in low voltage high frequency inverters, free wheeling and polarity protection applications.



ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter	Value	Unit		
V _{RRM}	Repetitive peak reverse voltage			30	V
I _{F(RMS)}	RMS forward current			32	Α
I _{F(AV)}	Average forward current	Tc = 130°C δ = 0.5	Per diode Per device	20 40	Α
I _{FSM}	Surge non repetitive forward current	tp = 10 ms 3	220	Α	
I _{RRM}	Peak repetitive reverse current	tp=2 µs squa	re F=1kHz	2	Α
P _{ARM}	Repetitive peak avalanche power $tp = 1\mu s$ $Tj = 25$ °C			5300	W
T _{stg}	Storage temperature range	- 65 to + 150	°C		
Tj	Maximum operating junction temperature *			150	°C
dV/dt	Critical rate of rise of reverse voltage (rated V _R , Tj = 25°C)			10000	V/µs

^{* :} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit	
R _{th(j-c)}	Junction to case TO-220AB - D ² PAK - I ² PAK	Per diode	1.6	°C/W
		Total	0.85	
R _{th(c)}		Coupling	0.1	°C/W

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Тур.	Max.	Unit
I _R *	Reverse leakage	Tj = 25°C	$V_R = V_{RRM}$		0.50	1.0	mA
	current	Tj = 125°C			170	350	
V _F *	Forward voltage drop	Tj = 25°C	I _F = 20 A		0.44	0.49	V
		Tj = 125°C	I _F = 20 A		0.35	0.40	
		Tj = 25°C	I _F = 40 A		0.52	0.61	
		Tj = 125°C	I _F = 40 A		0.46	0.55	

Pulse test: * tp = 380 μ s, δ < 2%

To evaluate the conduction losses use the following equation : $P = 0.25 \times I_{F(AV)} + 0.0075 I_{F}^{2}(RMS)$

Fig. 1: Conduction losses versus average current.

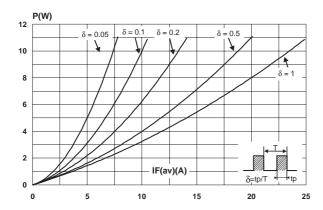


Fig. 3: Normalized avalanche power derating versus pulse duration.

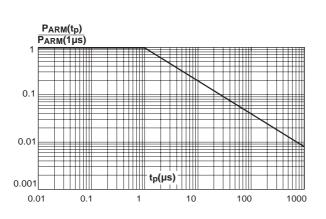


Fig. 2: Average forward current versus ambient temperature ($\delta = 0.5$).

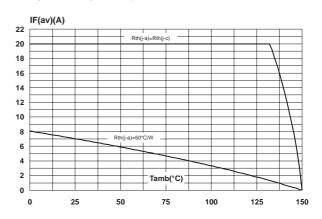


Fig. 4: Normalized avalanche power derating versus junction temperature.

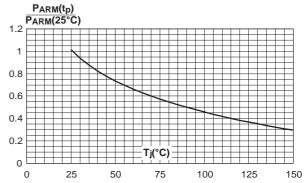


Fig. 5: Non repetitive surge peak forward current versus overload duration (maximum values).

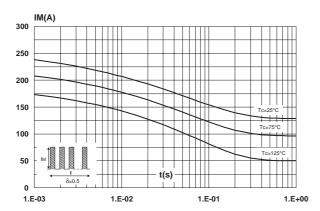


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values).

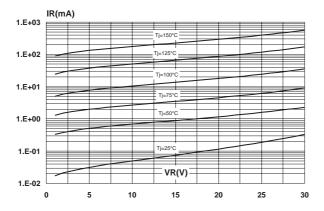


Fig. 9: Forward voltage drop versus forward current.

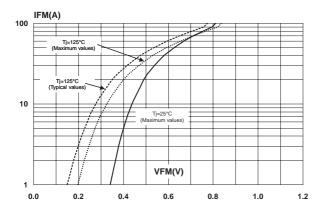


Fig. 6: Relative variation of thermal impedance junction to case versus pulse duration.

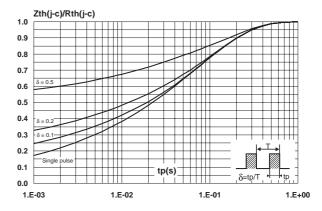


Fig. 8: Junction capacitance versus reverse voltage applied (typical values).

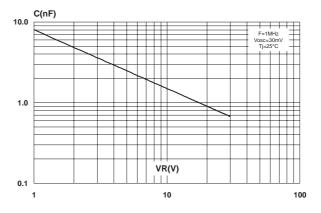
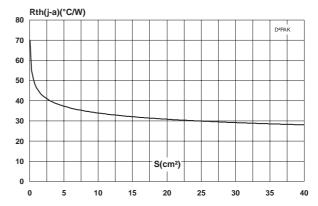
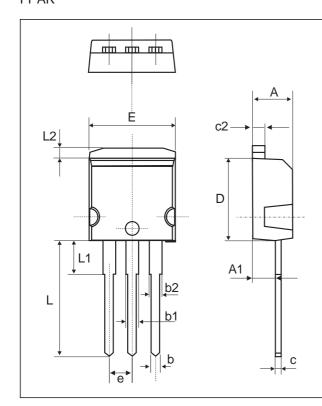


Fig. 10: Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, $Cu = 35\mu m$).



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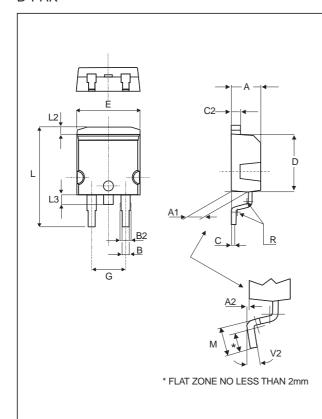
PACKAGE MECHANICAL DATA I2PAK



REF.	DIMENSIONS				
	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
А	4.40	4.60	0.173	0.181	
A1	2.49	2.69	0.098	0.106	
b	0.70	0.93	0.028	0.037	
b1	1.14	1.14 1.17		0.046	
b2	1.14	1.17	0.044	0.046	
С	0.45	0.60	0.018	0.024	
c2	1.23	1.36	0.048	0.054	
D	8.95	9.35	0.352	0.368	
е	2.40	2.70	0.094	0.106	
E	10.0	10.4	0.394	0.409	
L	13.1	13.6	0.516	0.535	
L1	3.48	3.78	0.137	0.149	
L2	1.27	1.40	0.050	0.055	

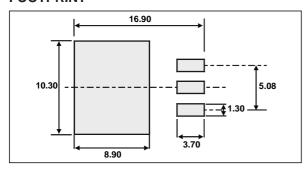
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PACKAGE MECHANICAL DATA D2PAK



REF.	DIMENSIONS				
	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
A1	2.49	2.69	0.098	0.106	
A2	0.03	0.23	0.001	0.009	
В	0.70	0.93	0.027	0.037	
B2	1.14	1.70	0.045	0.067	
С	0.45	0.60	0.017	0.024	
C2	1.23	1.36	0.048	0.054	
D	8.95	9.35	0.352	0.368	
Е	10.00	10.40	0.393	0.409	
G	4.88	5.28	0.192	0.208	
L	15.00	15.85	0.590	0.624	
L2	1.27	1.40	0.050	0.055	
L3	1.40	1.75	0.055	0.069	
М	2.40	3.20	0.094	0.126	
R	0.40	0.40 typ.		6 typ.	
V2	0°	8°	0°	8°	

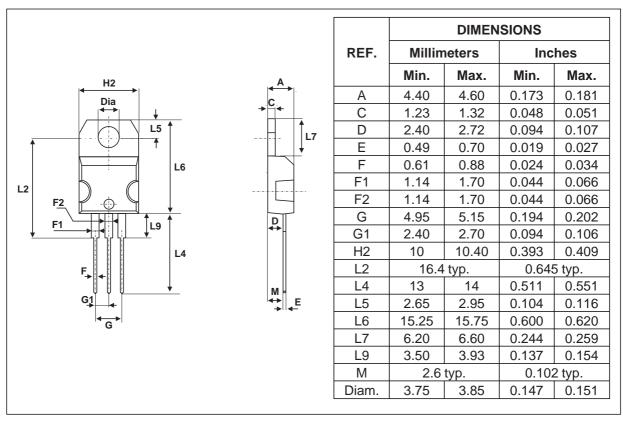
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PACKAGE MECHANICAL DATA

TO-220AB



■ COOLING METHOD : C

■ RECOMMENDED TORQUE VALUE: 0.55 M.N

MAXIMUM TORQUE VALUE: 0.70 M.N.

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS4030CT	STPS4030CT	TO-220AB	2.2 g	50	Tube
STPS4030CG	STPS4030CG	D²PAK	1.48 g	50	Tube
STPS4030CG-TR	STPS4030CG	D²PAK	1.48 g	1000	Tape & reel
STPS4030CR	STPS4030CR	I²PAK	1.49 g	50	Tube

■ EPOXY MEETS UL94,V0

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